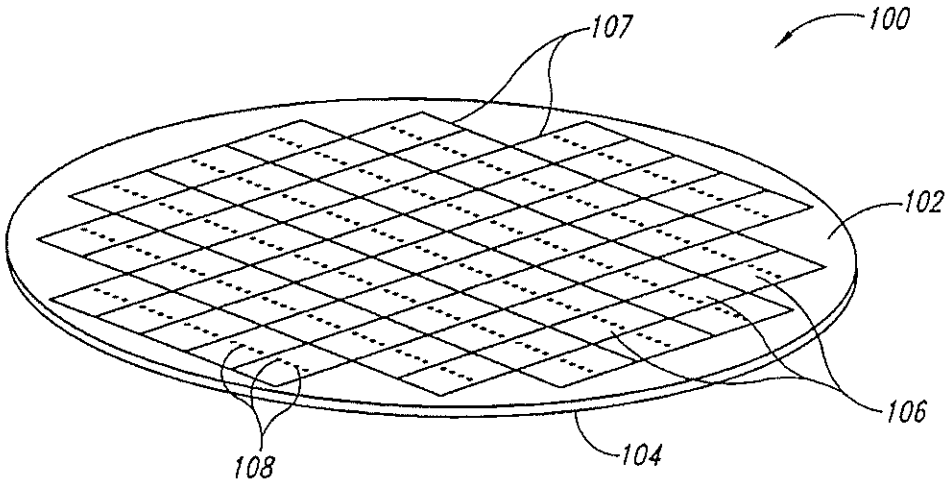

107
100
102
106
104
108

Fig. 1A

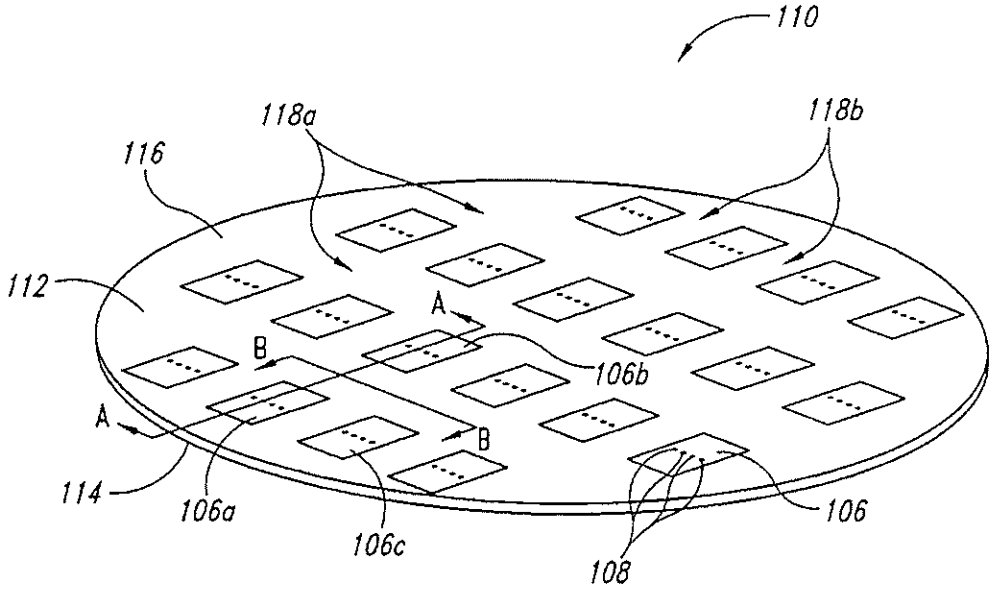

110
118a
118b
116
112
A
B
106b
A
B
114
106a
106c
106
108

Fig. 1B

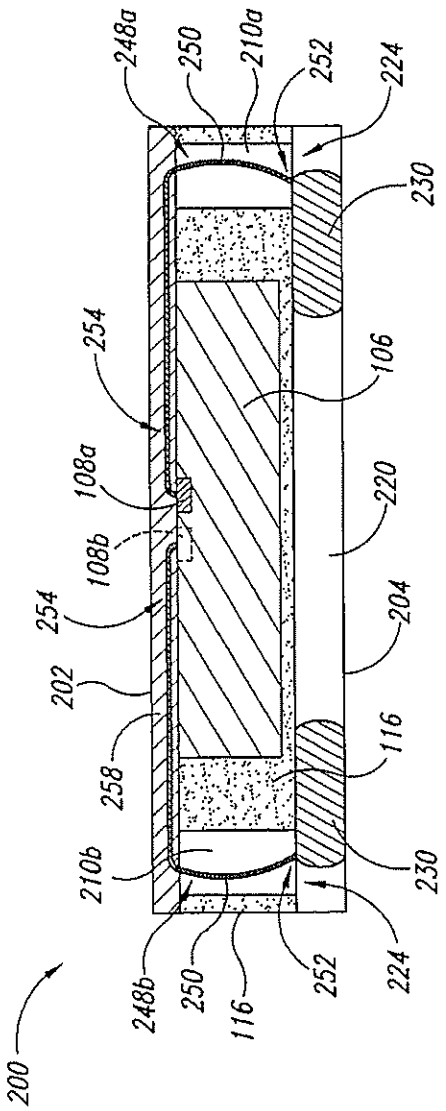

200
248b
250
116
252
224
230
210b
258
202
254
108b
108a
254
220
204
116
230
106
224
252
210a
250
248a

Fig. 2A

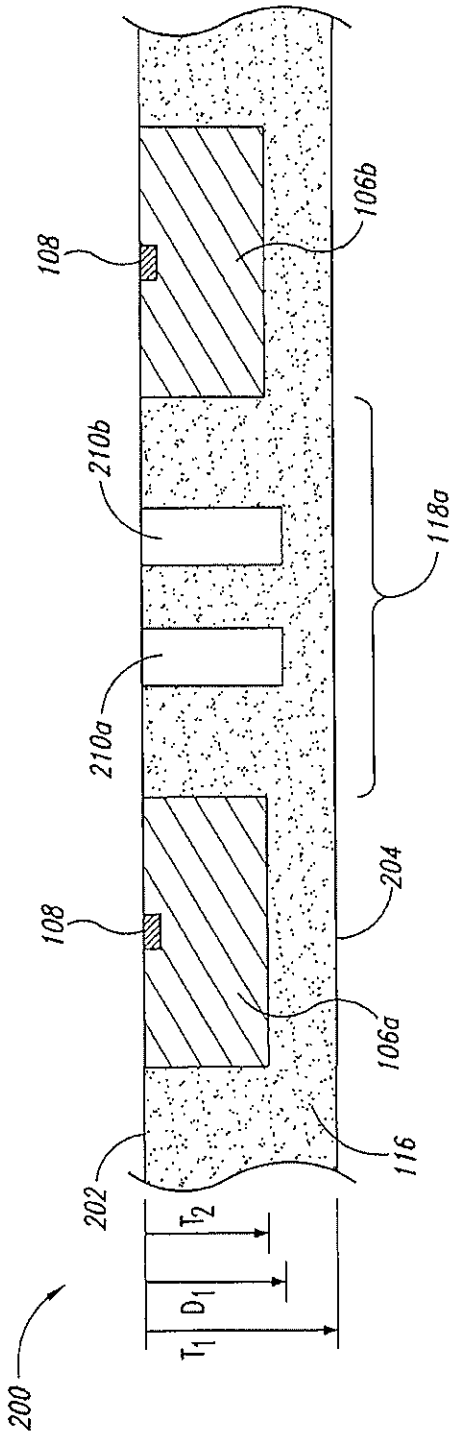

200
202
116
106a
204
108
210a
210b
108
106b
118a
T1
D1
T2

Fig. 2B

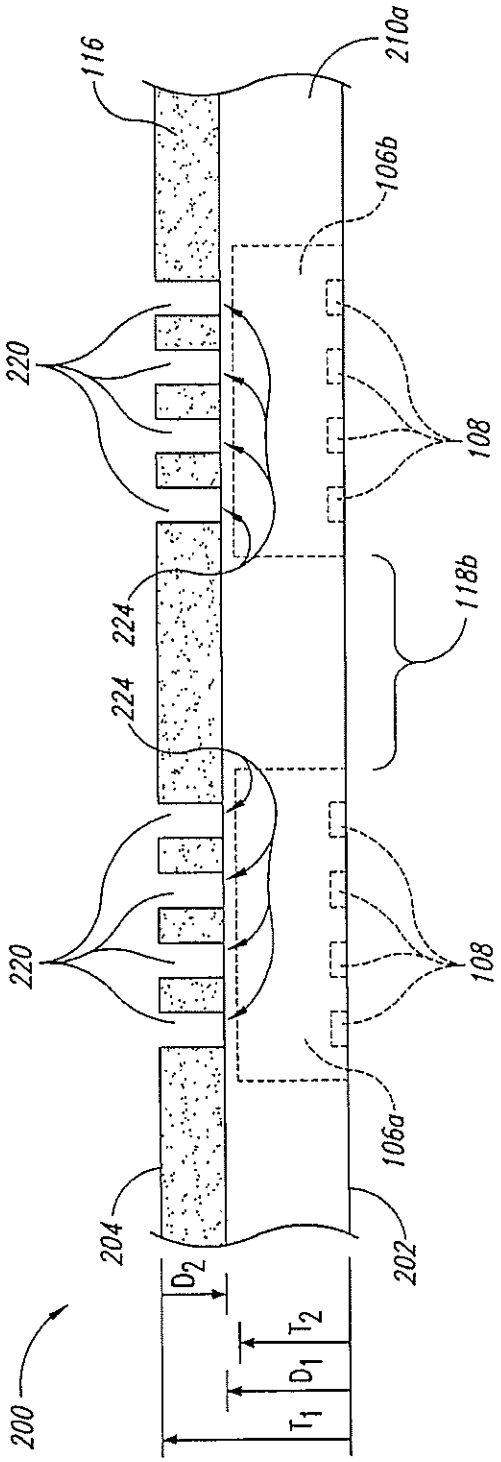

200
116
210a
106b
220
108
224
118b
224
220
108
106a
204
202
D_2
T_2
D_1
T_1

Fig. 2C

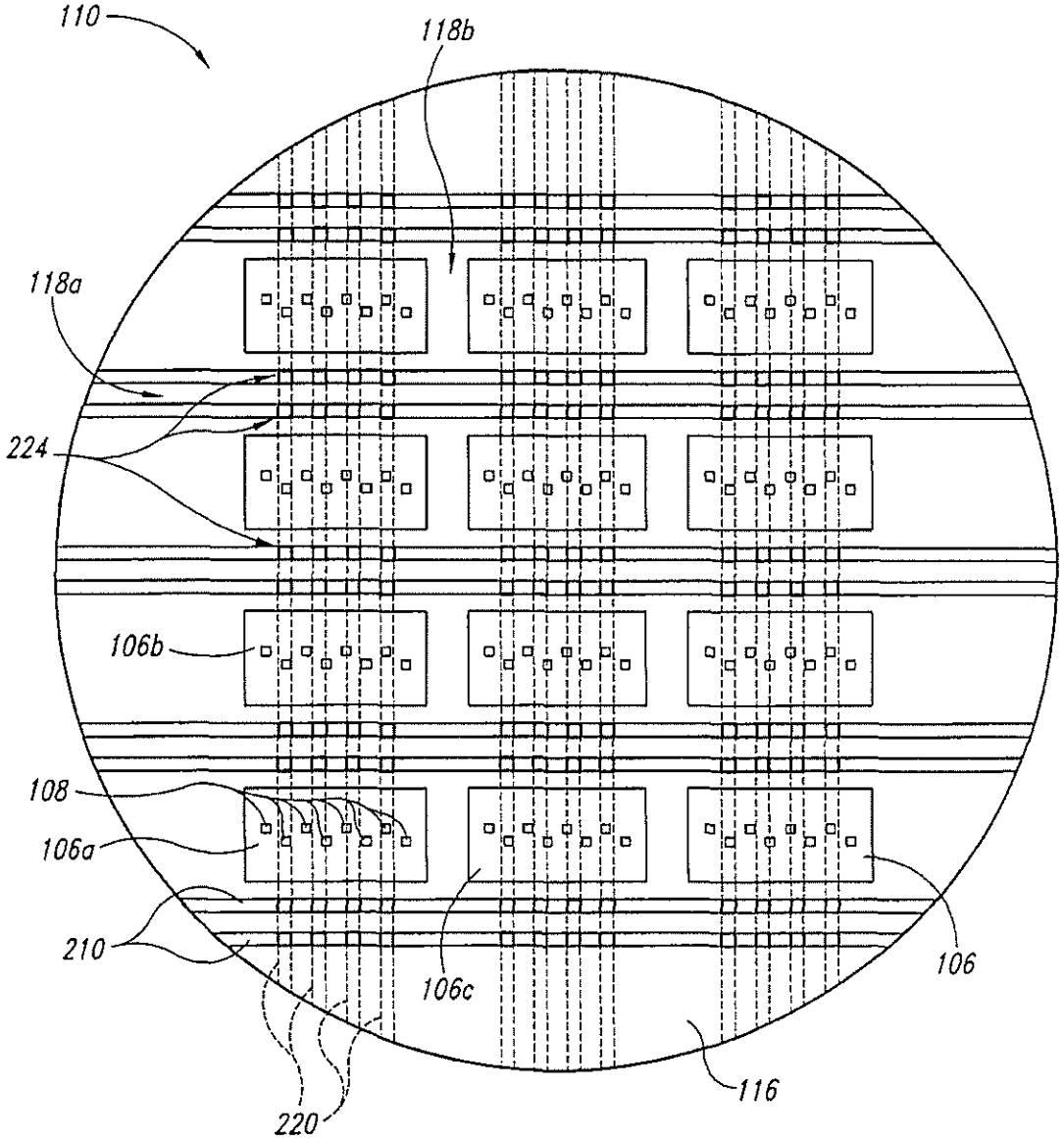


Fig. 2D

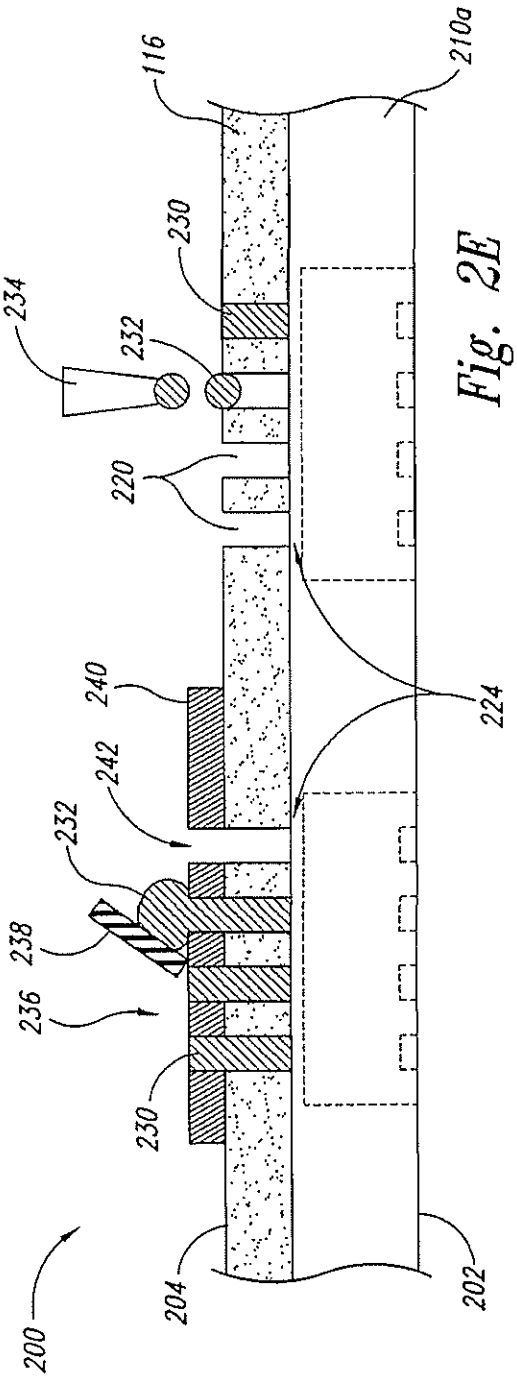

200
204
202
210a
116
230
234
232
220
240
242
232
238
236
230
224

Fig. 2E

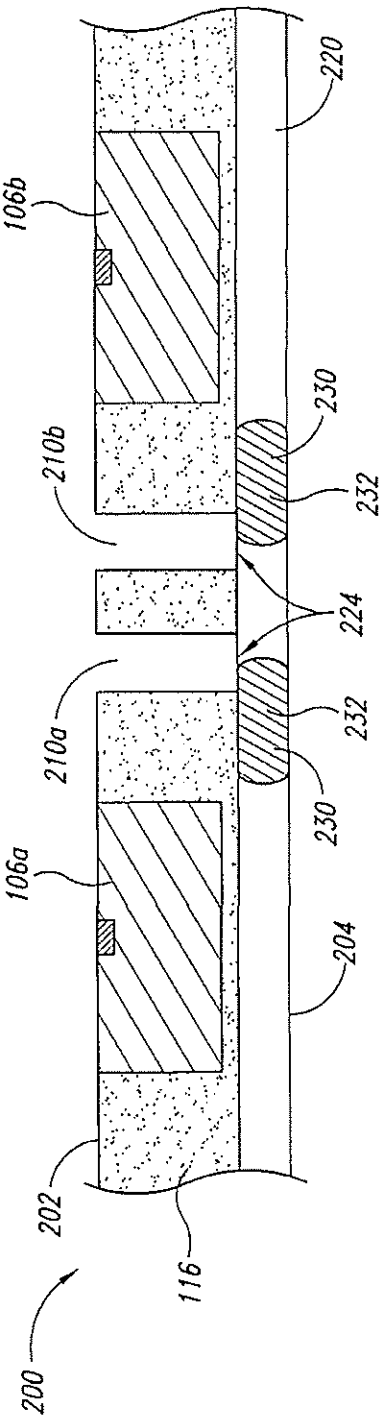

200
202
116
204
106a
210a
106b
210b
220
230
232
224
232
230

Fig. 2F

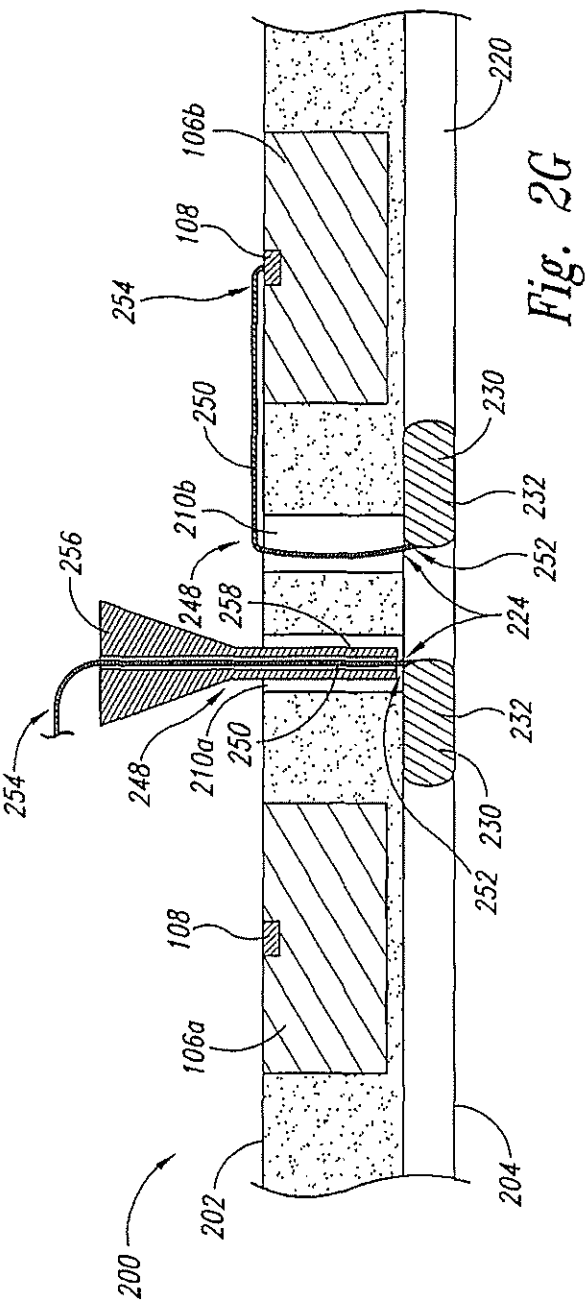

200
202
204
106a
106b
108
108
210a
210b
220
224
230
230
232
232
248
248
250
250
252
252
254
254
256
258

Fig. 2G

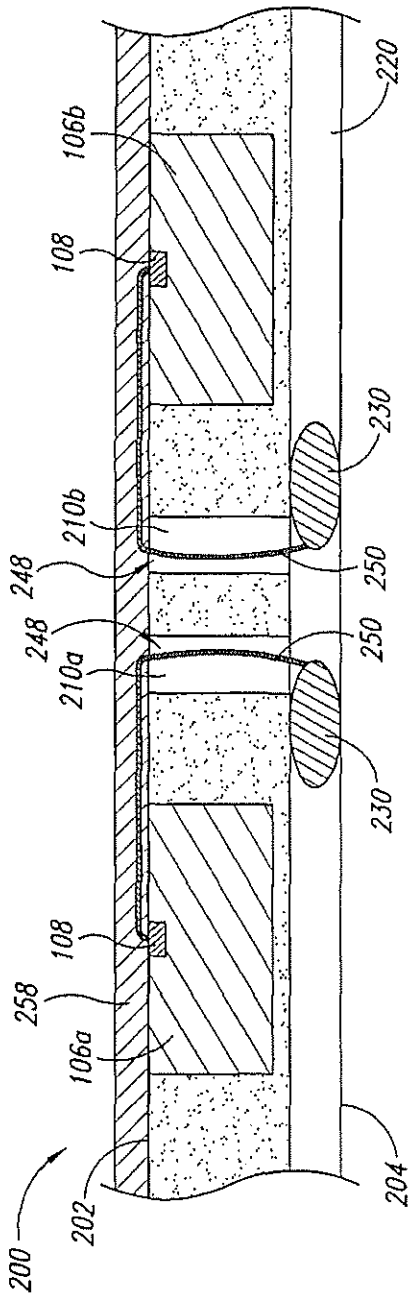

200
202
204
106a
106b
108
108
210a
210b
220
230
230
248
248
250
250
258

Fig. 2H

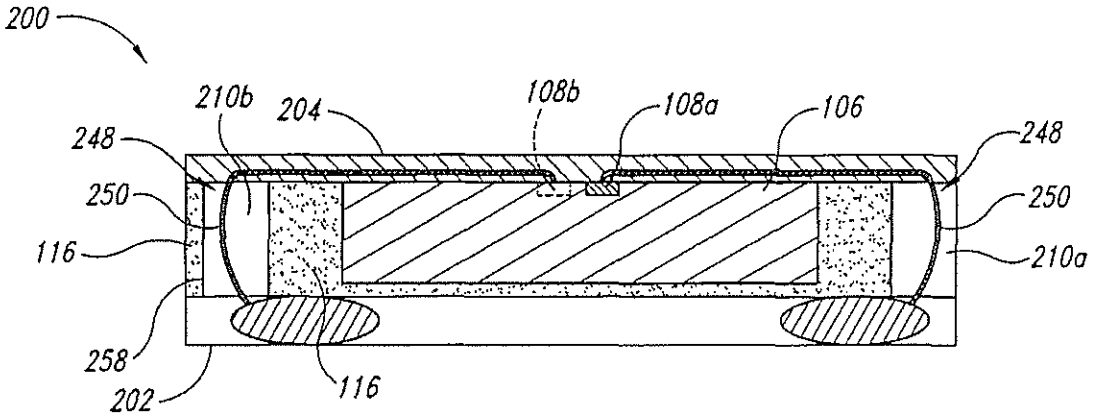

200
210b
204
108b
108a
106
248
248
250
250
116
210a
258
202
116

Fig. 2I

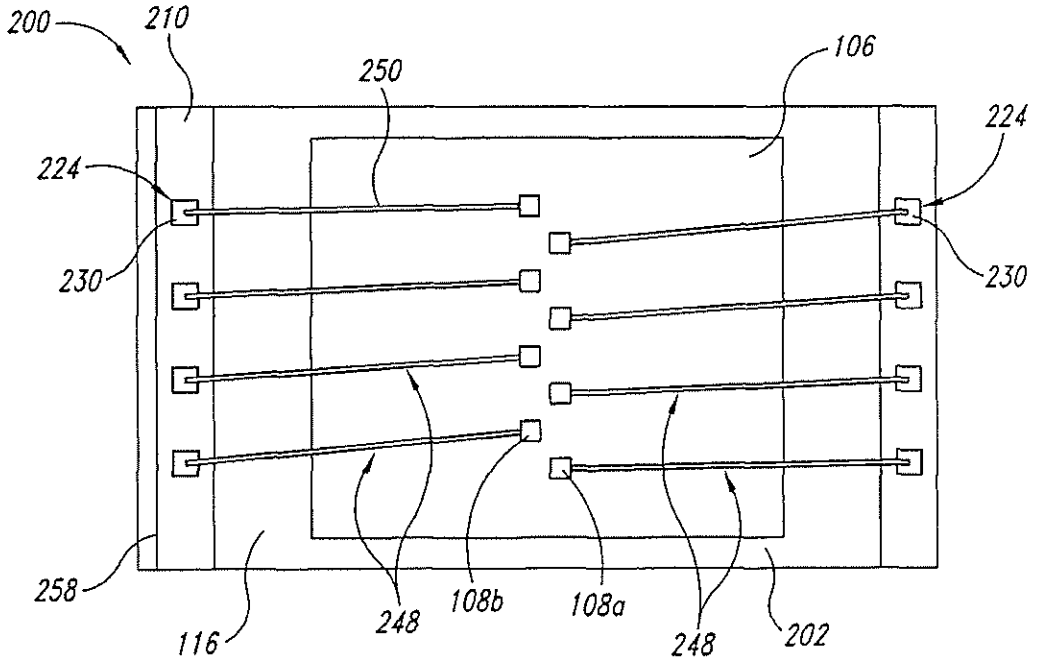

200
210
250
106
224
224
230
230
258
116
248
108b
108a
248
202

Fig. 2J

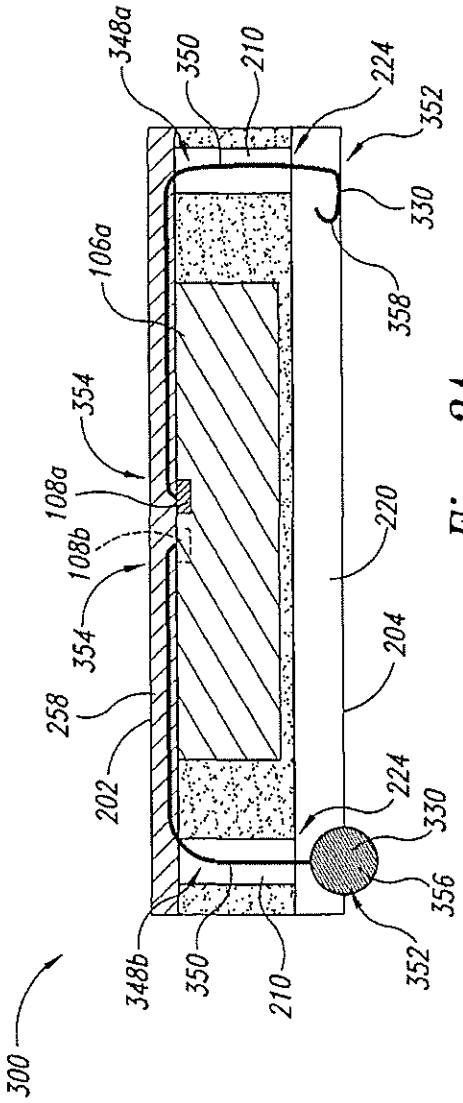

348a
350
210
224
352
330
358
106a
354
108a
108b
354
220
204
258
202
224
330
356
352
348b
350
210
300

Fig. 3A

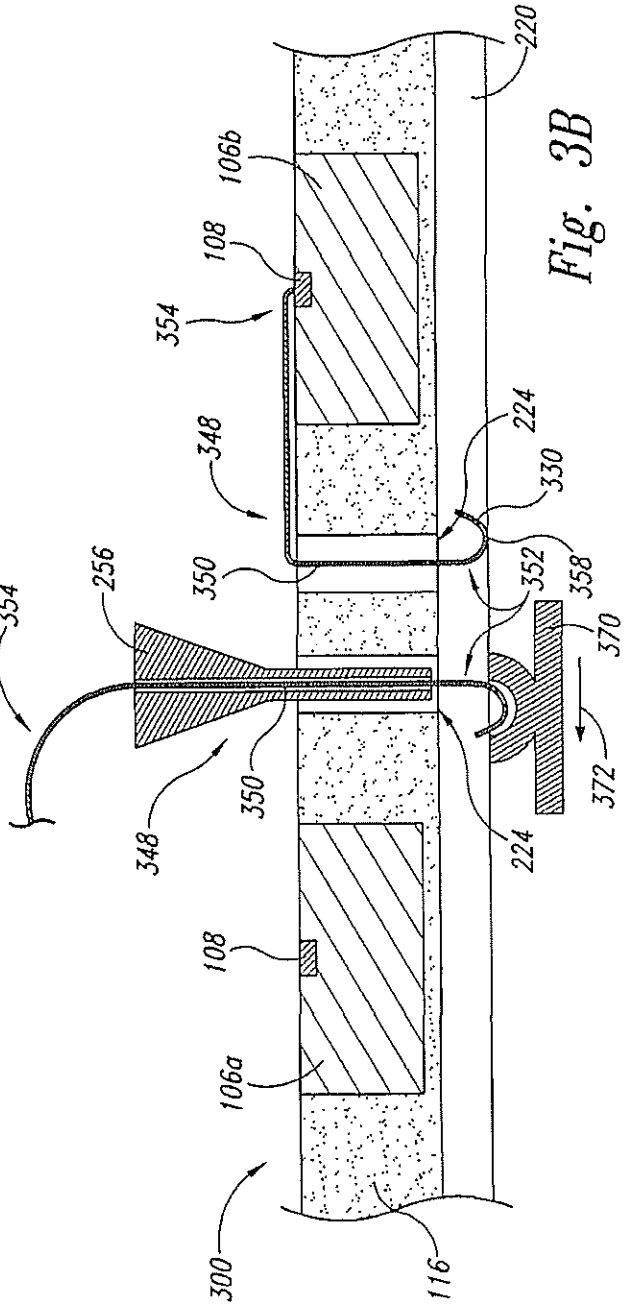

220
106b
108
354
348
224
330
352
358
350
256
354
370
372
348
350
224
108
106a
300
116

Fig. 3B

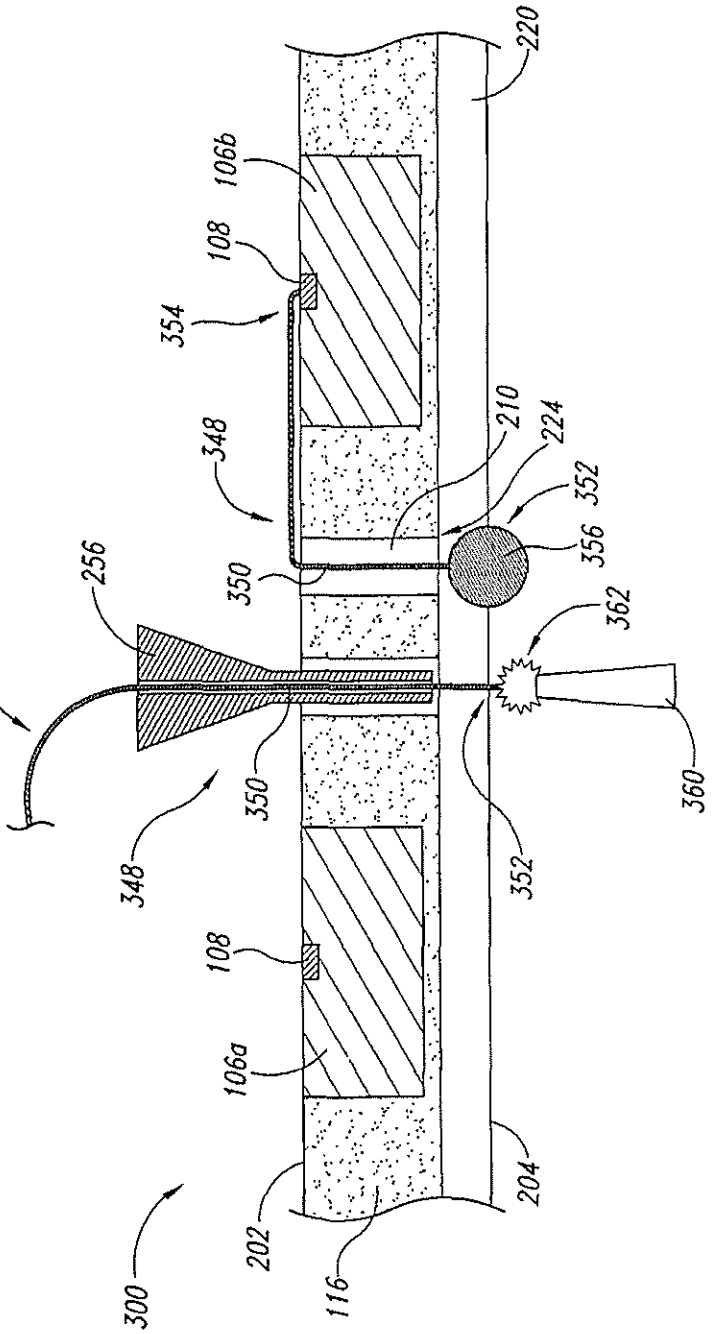

220
106b
108
354
348
210
224
352
356
350
256
354
362
360
348
350
352
108
106a
204
202
116
300

Fig. 3C

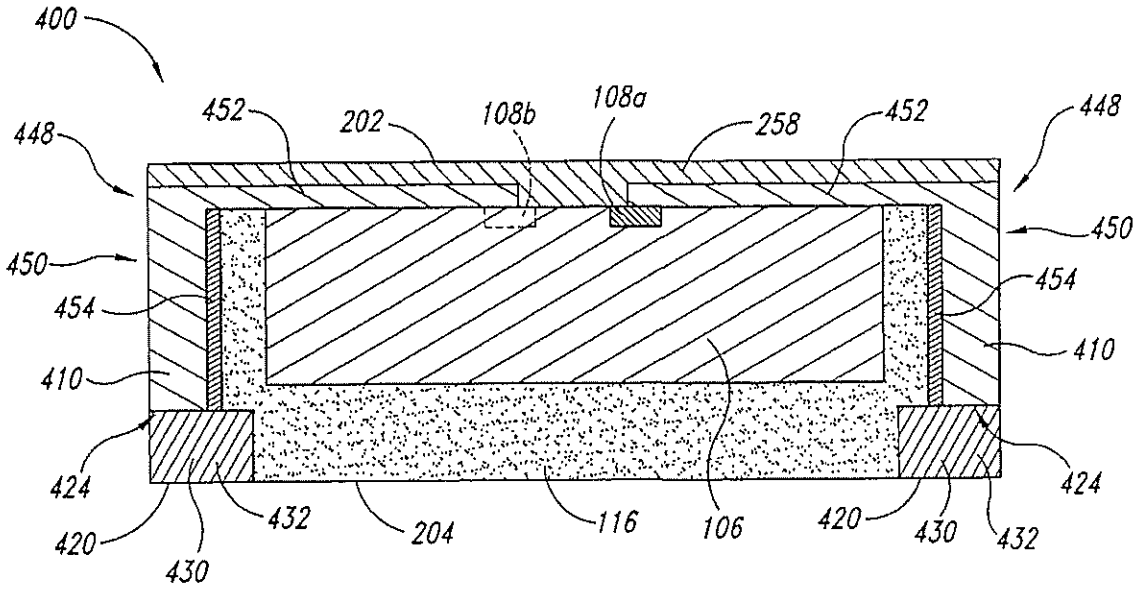

400
452
202
108b
108a
258
452
448
448
450
450
454
454
410
410
424
424
420
430
432
204
116
106
420
430
432

Fig. 4A

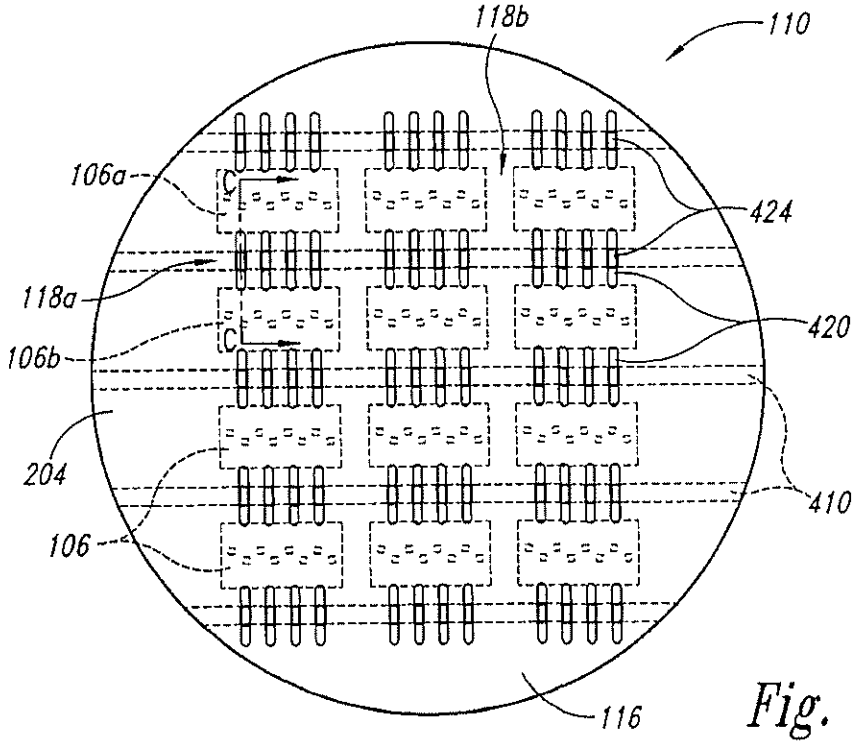

118b
110
106a
C
424
118a
420
C
106b
204
410
106
116

Fig. 4B

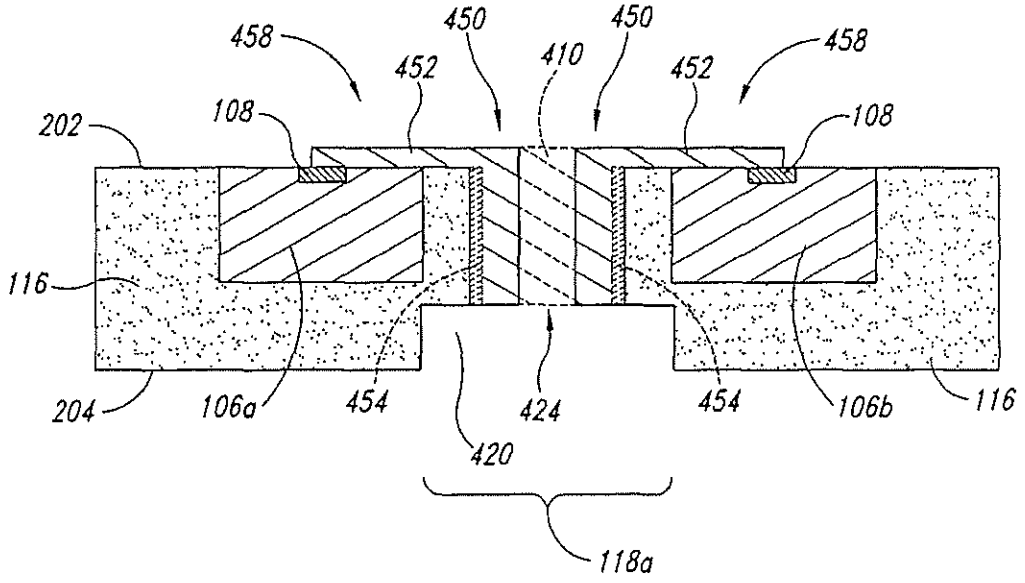

458
450
450
458
452
410
452
202
108
108
116
204
106a
454
424
454
106b
116
420
118a

Fig. 4C

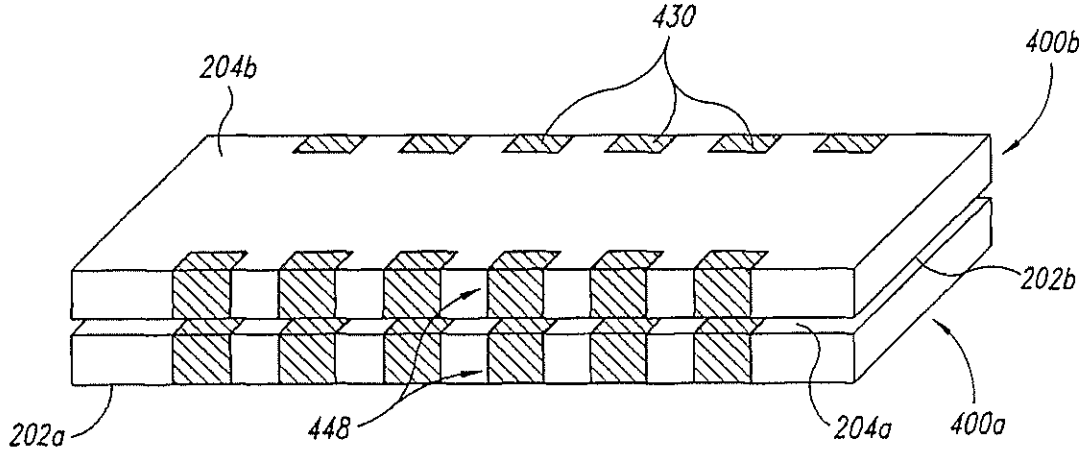

430
400b
204b
202b
448
202a
204a
400a

Fig. 4D

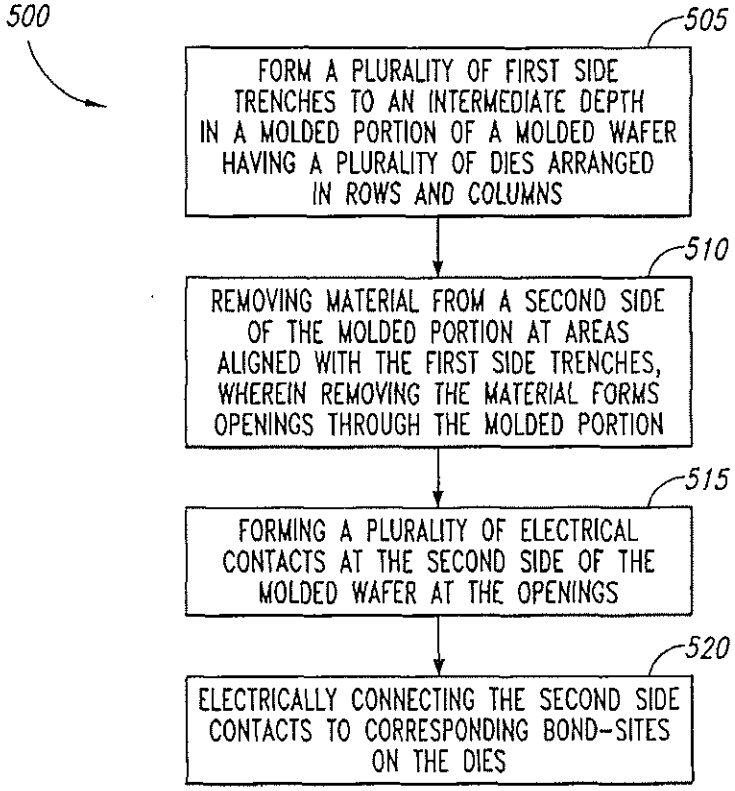

500
505
FORM A PLURALITY OF FIRST SIDE TRENCHES TO AN INTERMEDIATE DEPTH IN A MOLDED PORTION OF A MOLDED WAFER HAVING A PLURALITY OF DIES ARRANGED IN ROWS AND COLUMNS
510
REMOVING MATERIAL FROM A SECOND SIDE OF THE MOLDED PORTION AT AREAS ALIGNED WITH THE FIRST SIDE TRENCHES, WHEREIN REMOVING THE MATERIAL FORMS OPENINGS THROUGH THE MOLDED PORTION
515
FORMING A PLURALITY OF ELECTRICAL CONTACTS AT THE SECOND SIDE OF THE MOLDED WAFER AT THE OPENINGS
520
ELECTRICALLY CONNECTING THE SECOND SIDE CONTACTS TO CORRESPONDING BOND-SITES ON THE DIES

Fig. 5

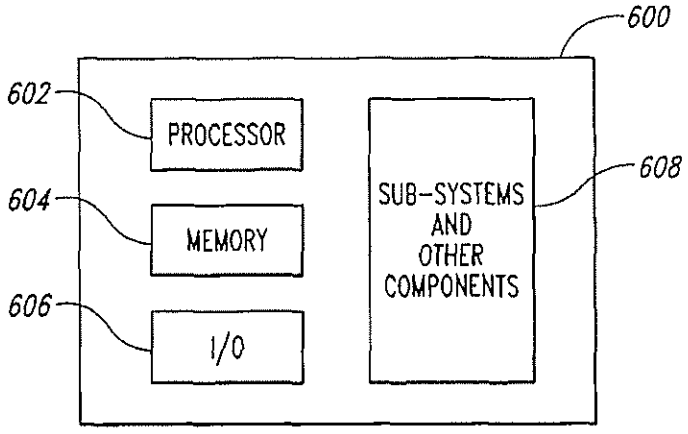

600
602
PROCESSOR
604
MEMORY
606
I/O
SUB-SYSTEMS AND OTHER COMPONENTS
608

Fig. 6